NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The terminals are gold plated.
5. This drawing does not comply with MIL STD 1835. Do not use this package for compliant product.
6. Metal lid is connected to back side pad metatilation.
EXAMPLE BOARD LAYOUT

HKU0010A

CFP - 2.63mm max height

CERAMIC DUAL FLATPACK

HEATSINK LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X
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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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